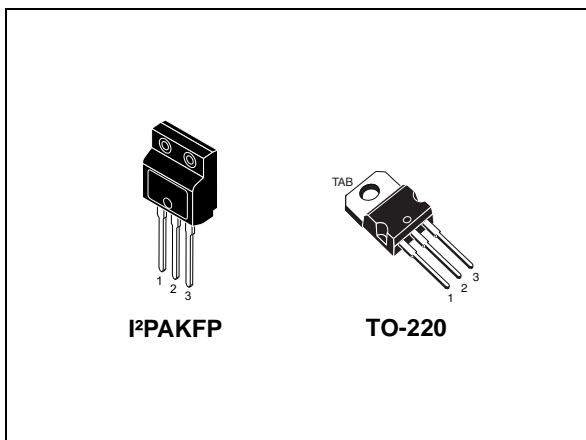
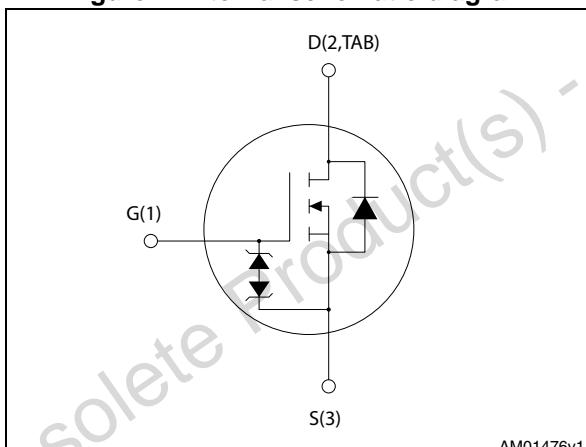


N-channel 620 V, 1.28  $\Omega$  typ., 5.0 A Power MOSFET  
in I<sup>2</sup>PAKFP and TO-220 packages

Datasheet – preliminary data



**Figure 1. Internal schematic diagram**



## Features

Order codes	V <sub>DS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>	P <sub>TOT</sub>
STFILED625	620 V	1.6 $\Omega$	5.0 A	25 W
STPLED625				70 W

- 100% avalanche tested
- Extremely high dv/dt capability
- Gate charge minimized
- Very low intrinsic capacitance
- Improved diode reverse recovery characteristics
- Zener-protected

## Applications

- LED lighting applications

## Description

These Power MOSFETs boast extremely low on-resistance and very good dv/dt capability, rendering them suitable for buck-boost and flyback topologies.

**Table 1. Device summary**

Order codes	Marking	Package	Packaging
STFILED625	LED625	I <sup>2</sup> PAKFP (TO-281)	Tube
STPLED625		TO-220	

## Contents

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3	<b>Test circuits</b>	9
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# 1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		I <sup>2</sup> PAKFP	TO-220	
V <sub>DS</sub>	Drain- source voltage	620		V
V <sub>GS</sub>	Gate- source voltage	± 30		V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	5.0 <sup>(1)</sup>	5.0	A
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	3.5 <sup>(1)</sup>	3.5	A
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	20.0 <sup>(1)</sup>	20.0	A
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	70	25	W
I <sub>AR</sub>	Avalanche current, repetitive or not-repetitive (pulse width limited by T <sub>J</sub> max)	4.2		A
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>J</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	120		mJ
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	12		V/ns
di/dt <sup>(3)</sup>	Diode reverse recovery current slope	400		A/μs
V <sub>ISO</sub>	Insulation withstand voltage (AC)	2500		V
T <sub>J</sub> T <sub>stg</sub>	Operating junction temperature Storage temperature	- 55 to 150		°C

1. Limited only by maximum temperature allowed
2. Pulse width limited by safe operating area
3. I<sub>SD</sub> ≤ I<sub>D</sub>, peak V<sub>DS</sub> ≤ V<sub>(BR)DSS</sub>, V<sub>DD</sub> = 80% V<sub>(BR)DSS</sub>

Table 3. Thermal data

Symbol	Parameter	Value		Unit
		I <sup>2</sup> PAKFP	TO-220	
R <sub>thj-case</sub>	Thermal resistance junction-case max	5	1.79	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-amb max	62.50		°C/W

## 2 Electrical characteristics

( $T_{case} = 25^\circ C$  unless otherwise specified)

**Table 4. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	620			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = 620 \text{ V}$ $V_{DS} = 620 \text{ V}, T_C = 125^\circ C$			1 50	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0$			$\pm 10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 50 \mu\text{A}$	3	3.6	4.5	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 2.1 \text{ A}$		1.28	1.6	$\Omega$

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance			690		pF
$C_{oss}$	Output capacitance	$V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0$	-	52	-	pF
$C_{rss}$	Reverse transfer capacitance			8.5		pF
$C_{oss \text{ eq}}^{(1)}$	Equivalent output capacitance	$V_{GS} = 0, V_{DS} = 0 \text{ to } 496 \text{ V}$		16.6		pF
$R_g$	Gate input resistance	$f=1 \text{ MHz}$ open drain	-	4	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 496 \text{ V}, I_D = 4.2 \text{ A}, V_{GS} = 10 \text{ V}$		27		nC
$Q_{gs}$	Gate-source charge		-	4	-	nC
$Q_{gd}$	Gate-drain charge	(see Figure 18)		16		nC

1.  $C_{oss \text{ eq}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$t_{d(on)}$	Turn-on delay time			12		ns
$t_r$	Rise time			8		ns
$t_{d(off)}$	Turn-off-delay time	$V_{DD} = 310 \text{ V}, I_D = 4.2 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	40	-	ns
$t_f$	Fall time	(see Figure 17)		21		ns

**Table 7. Source drain diode**

<b>Symbol</b>	<b>Parameter</b>	<b>Test conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max</b>	<b>Unit</b>
$I_{SD}$ $I_{SDM}^{(1)}$	Source-drain current Source-drain current (pulsed)		-		4.2 16.8	A A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 4.2 \text{ A}, V_{GS} = 0$	-		1.5	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 4.2 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$ (see Figure 19)	-	290 1900 13		ns nC A
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 4.2 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$ $T_J = 150^\circ\text{C}$ (see Figure 19)	-	320 2200 14		ns nC A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

**Table 8. Gate-source Zener diode**

<b>Symbol</b>	<b>Parameter</b>	<b>Test conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1 \text{ mA}, I_D = 0$	30	-	-	V

The built-in back-to-back Zener diodes have been specifically designed to enhance not only the device's ESD capability, but also to make them capable of safely absorbing any voltage transients that may occasionally be applied from gate to source. In this respect, the Zener voltage is appropriate to achieve efficient and cost-effective protection of device integrity. The integrated Zener diodes thus eliminate the need for external components.

## 2.1 Electrical characteristics (curves)

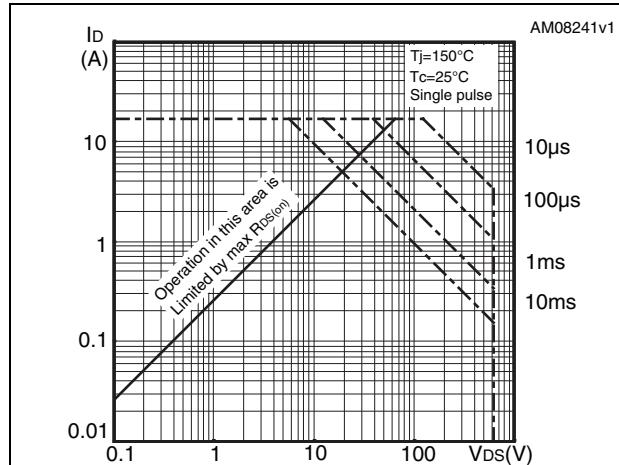
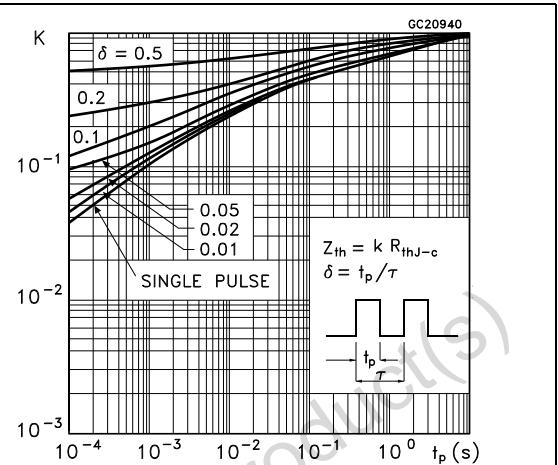
Figure 2. Safe operating area for I<sup>2</sup>PAKFPFigure 3. Thermal impedance for I<sup>2</sup>PAKFP

Figure 4. Safe operating area for TO-220

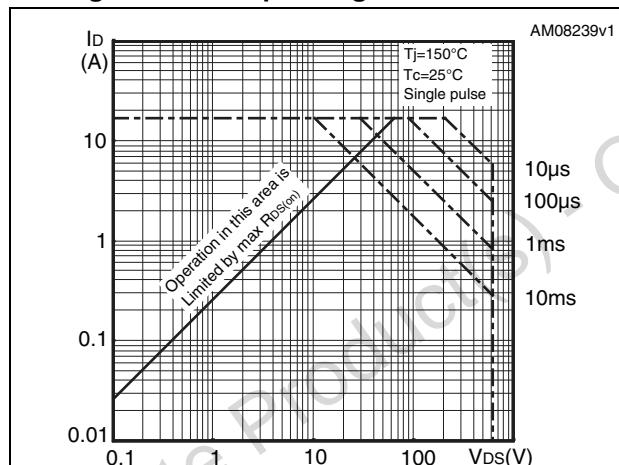


Figure 5. Thermal impedance TO-220

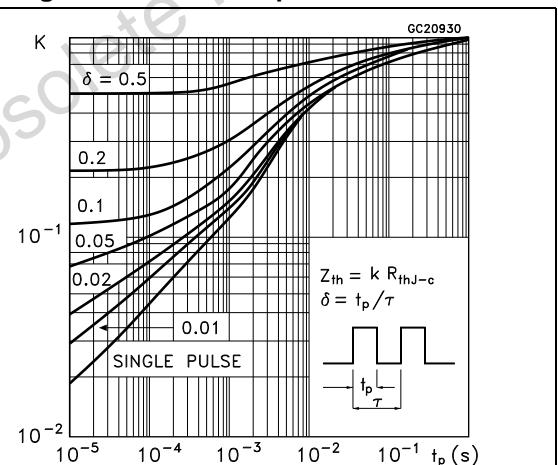


Figure 6. Output characteristics

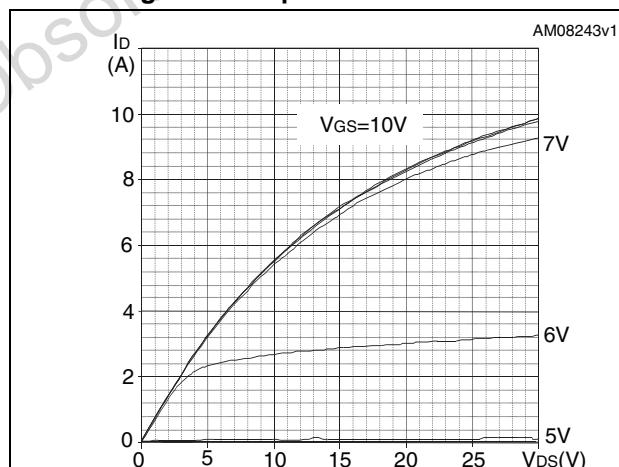
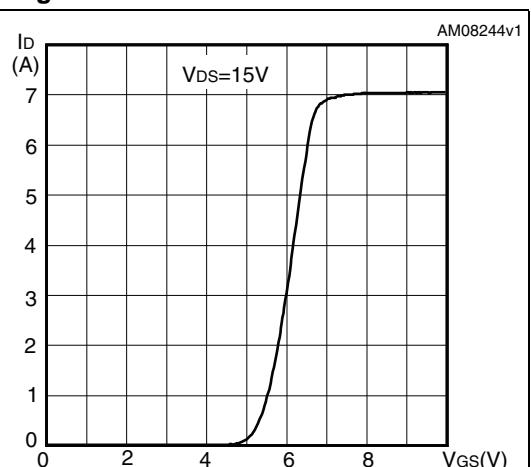
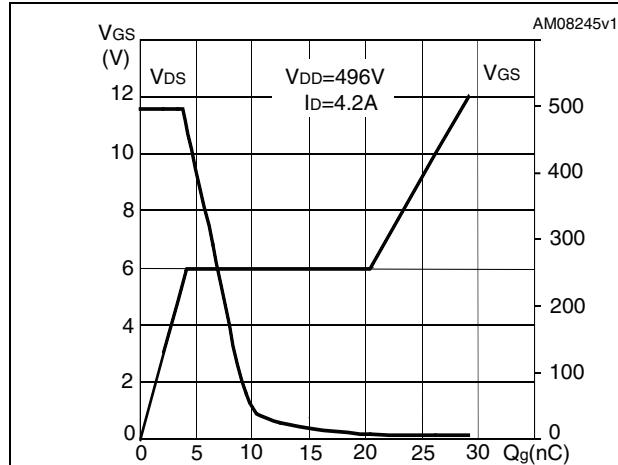
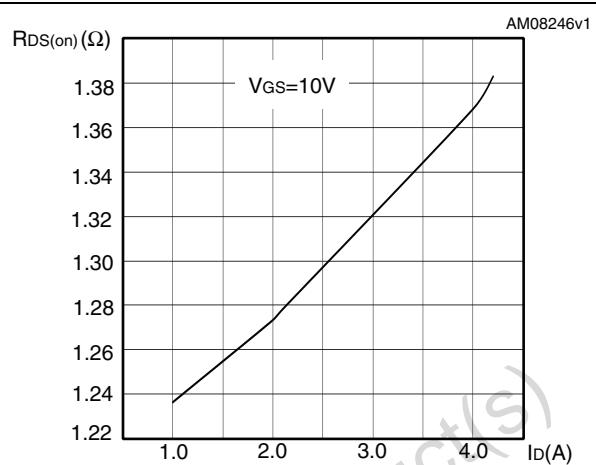
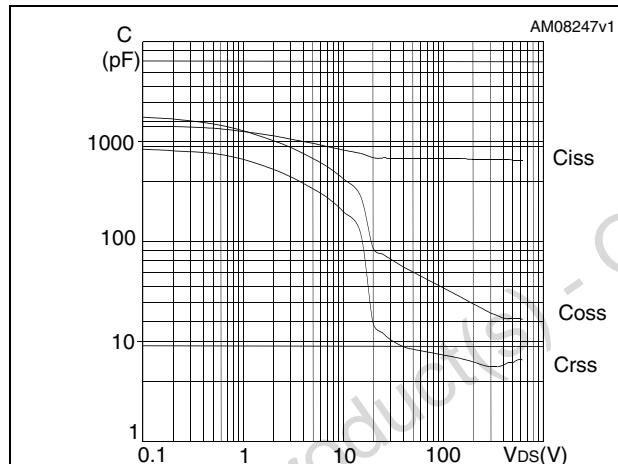
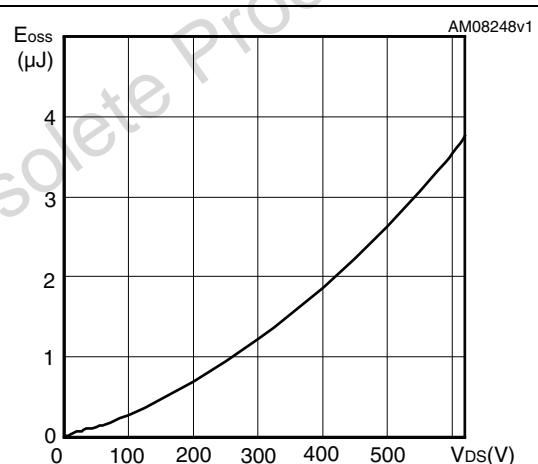
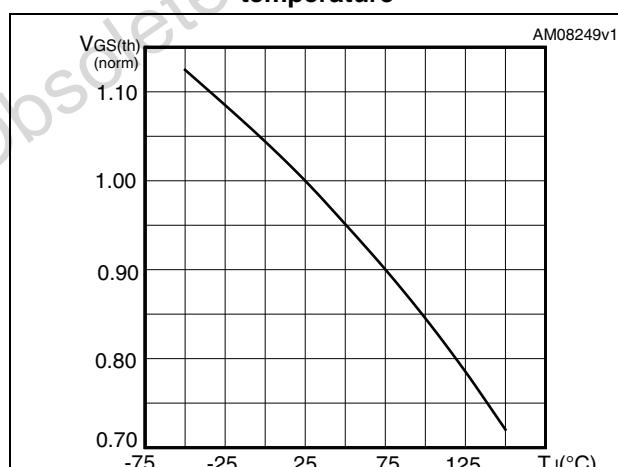
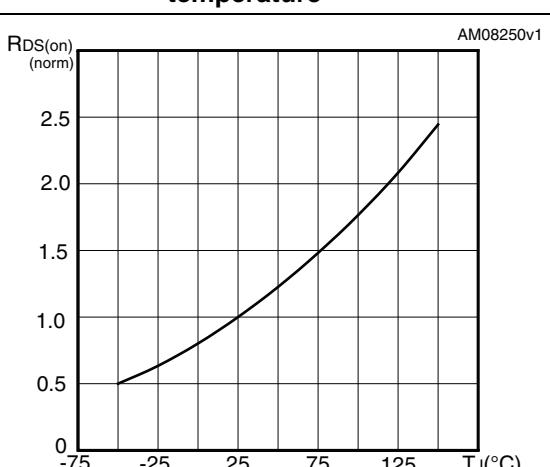
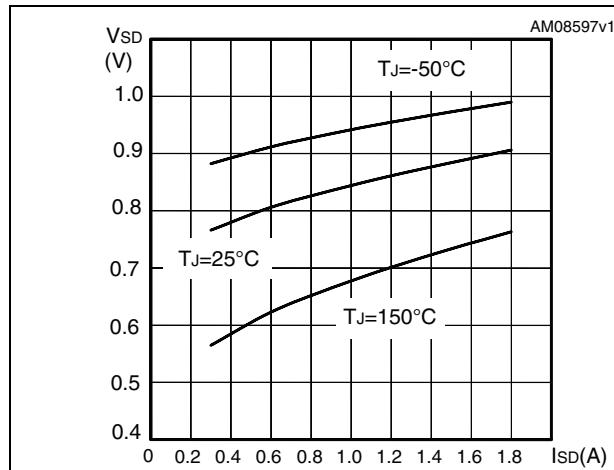
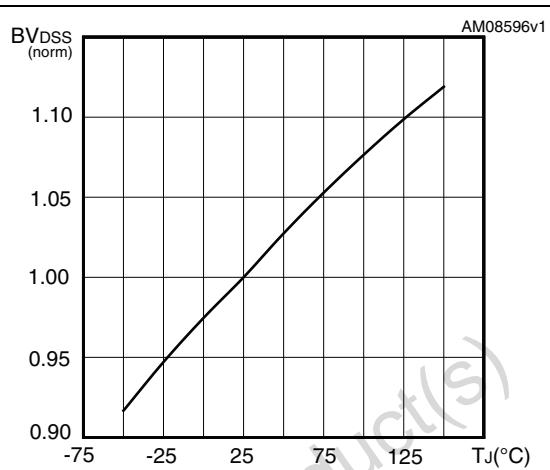
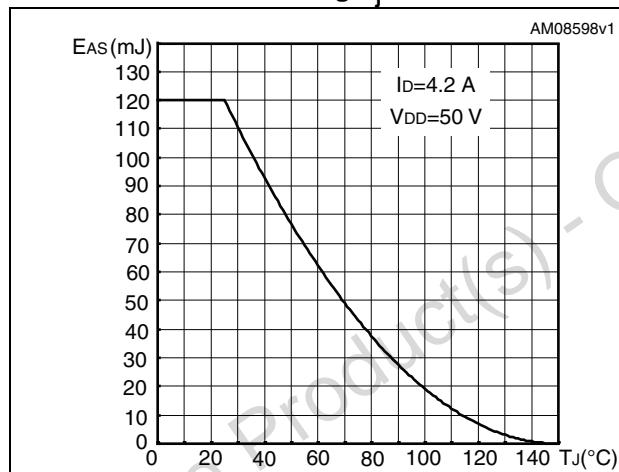


Figure 7. Transfer characteristics

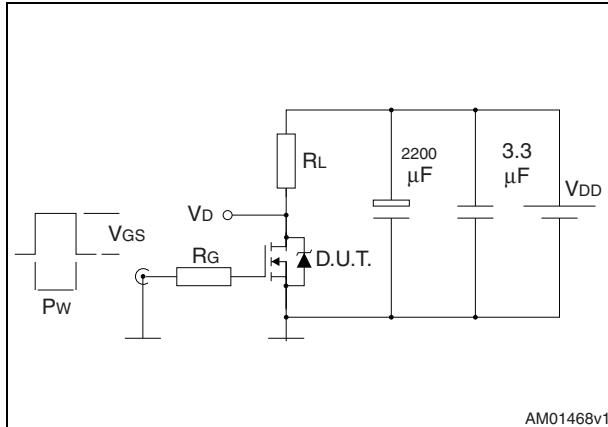


**Figure 8. Gate charge vs gate-source voltage****Figure 9. Static drain-source on-resistance****Figure 10. Capacitance variations****Figure 11. Output capacitance stored energy****Figure 12. Normalized gate threshold voltage vs temperature****Figure 13. Normalized on-resistance vs temperature**

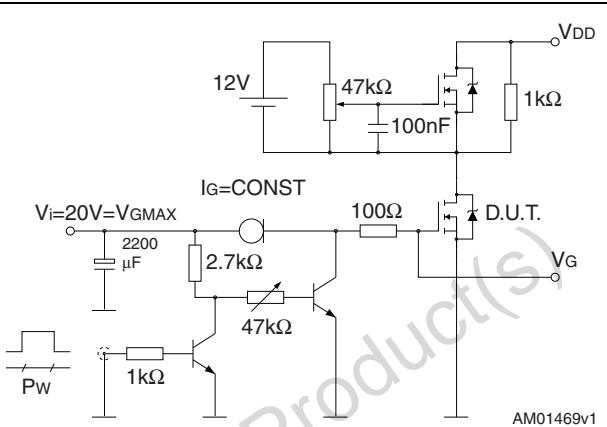
**Figure 14. Source-drain diode forward characteristics****Figure 15. Normalized  $B_{VDSS}$  vs temperature****Figure 16. Maximum avalanche energy vs starting  $T_j$** 

### 3 Test circuits

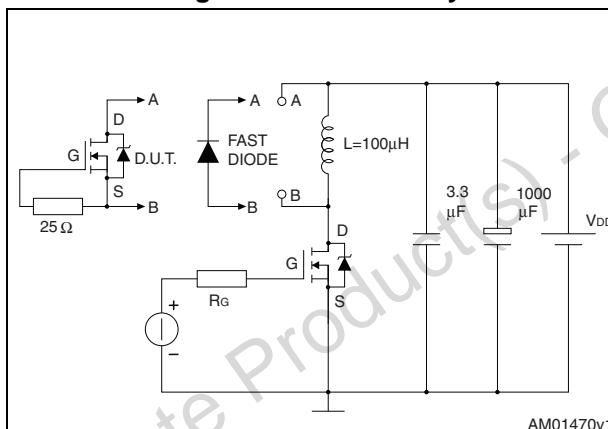
**Figure 17. Switching times test circuit for resistive load**



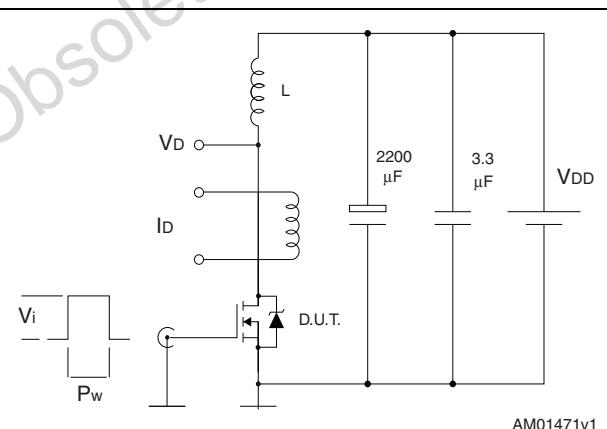
**Figure 18. Gate charge test circuit**



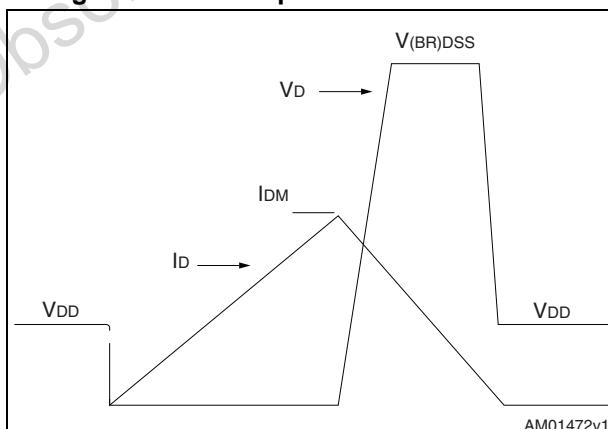
**Figure 19. Test circuit for inductive load switching and diode recovery times**



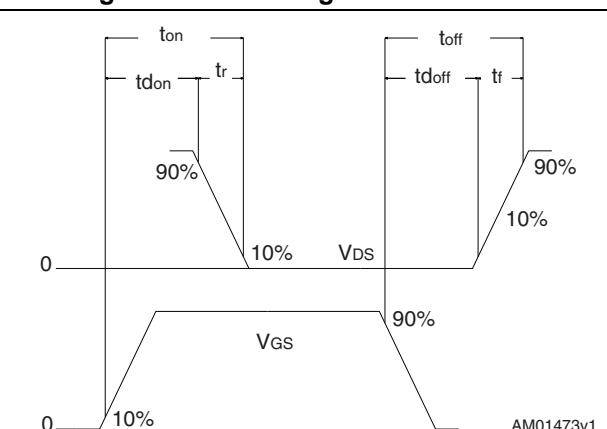
**Figure 20. Unclamped inductive load test circuit**



**Figure 21. Unclamped inductive waveform**



**Figure 22. Switching time waveform**

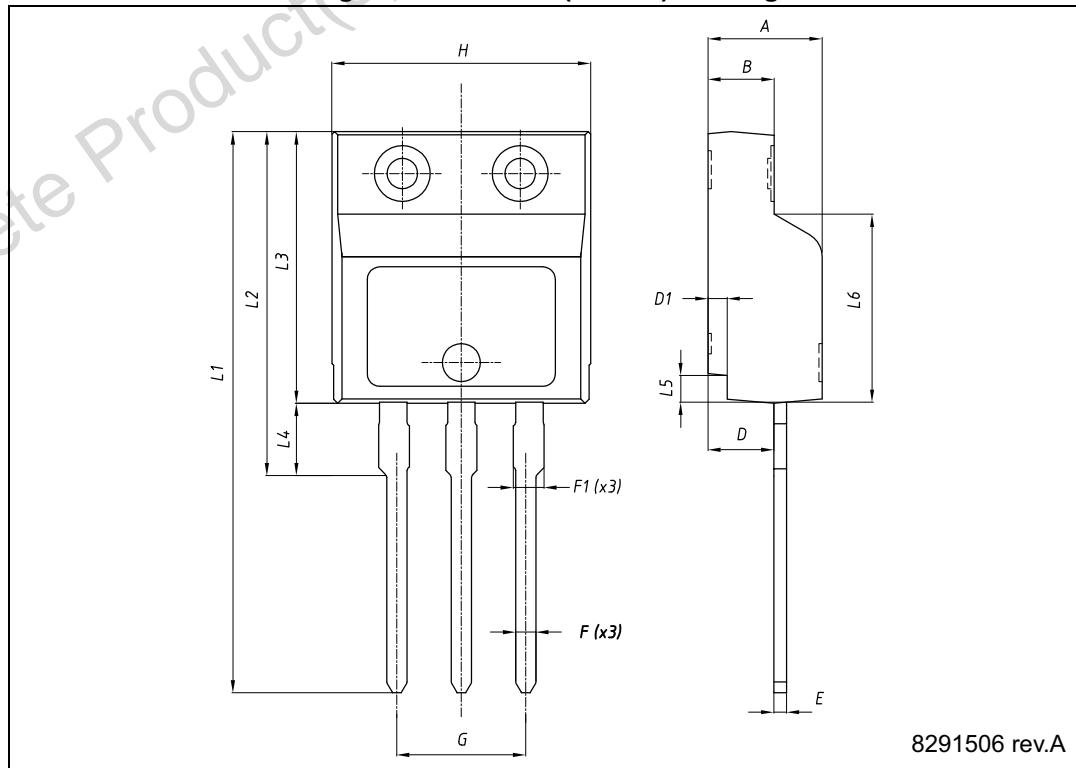


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
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**Table 9. I<sup>2</sup>PAKFP (TO-281) mechanical data**

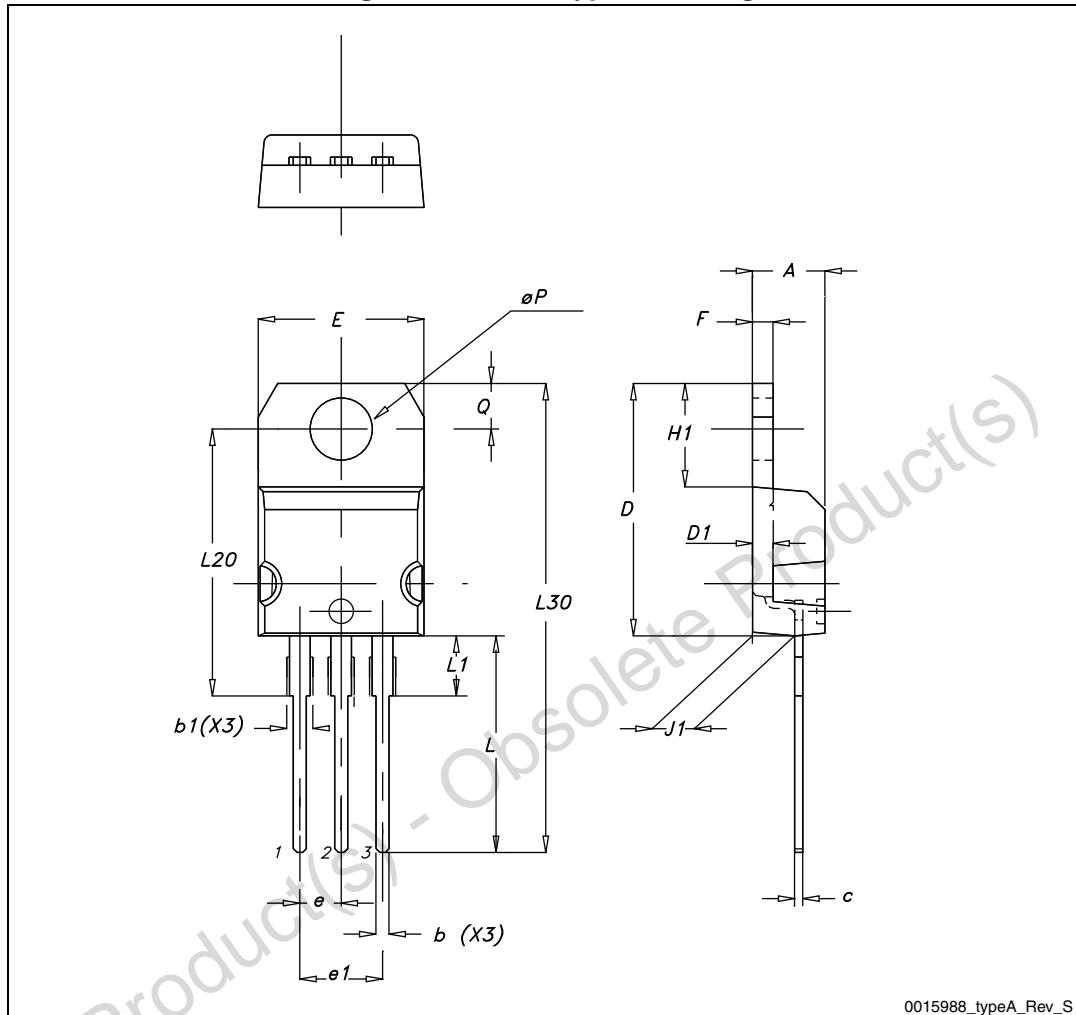
Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
D1	0.65		0.85
E	0.45		0.70
F	0.75		1.00
F1			1.20
G	4.95	-	5.20
H	10.00		10.40
L1	21.00		23.00
L2	13.20		14.10
L3	10.55		10.85
L4	2.70		3.20
L5	0.85		1.25
L6	7.30		7.50

**Figure 23. I<sup>2</sup>PAKFP (TO-281) drawing**

**Table 10. TO-220 type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Figure 24. TO-220 type A drawing



## 5 Revision history

Table 11. Document revision history

Date	Revision	Changes
25-Mar-2013	1	First release.

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